



ECCOBOND DS7300

July 2011

PRODUCT DESCRIPTION

ECCOBOND DS7300 provides the following product characteristics:

Technology	Epoxy
Appearance	White
Components	One-component
Product Benefits	• Excellent resistance to water permeation • Low viscosity • Protects against humidity and oxygen • Non-conductive
Cure	Heat cure
Application	Sealing

ECCOBOND DS7300 non-conductive epoxy perimeter sealant is designed to be used in display applications.

TYPICAL PROPERTIES OF UNCURED MATERIAL

Viscosity, Cone & Plate, @ 25 °C mPa·s (cP):

Plate 2 cm @ Shear rate 15 s⁻¹ 1,200

Shelf Life:

@ -25 to -18, °C, months 6

@ 18 to 25, °C, hours 24

Flash Point - See MSDS

TYPICAL CURING PERFORMANCE

Recommended Cure Schedule

60 minutes @ 70°C

Note: Ramp-up to 70°C is not included above.

The above cure profiles are guideline recommendations. Cure conditions (time and temperature) may vary based on customers' experience and their application requirements, as well as customer curing equipment, oven loading and actual oven temperatures.

Shrinkage on Cure

Cure Shrinkage, % 4.4

TYPICAL PROPERTIES OF CURED MATERIAL

Physical Properties:

Water Vapor Permeability Coefficient, g.mil / 100 in² :

24 hrs, 50°C/100% RH 6.3

GENERAL INFORMATION

For safe handling information on this product, consult the Material Safety Data Sheet, (MSDS).

This product is not recommended for use in pure oxygen and/or oxygen rich systems and should not be selected as a sealant for chlorine or other strong oxidizing materials.

Not for product specifications

The technical data contained herein are intended as reference only. Please contact your local quality department for assistance and recommendations on specifications for this product.

THAWING:

1. Allow container to reach room temperature before use.
2. Thaw material prior to use. A 10 cc syringe will thaw in approximately 30 minutes; a 30 cc syringe in 60 minutes.

DIRECTIONS FOR USE

1. For best results, dispense onto substrate warmed to ≤60°C and the needle tip to ≤50°C.
2. The viscosity of ECCOBOND DS7300 is very stable at room temperature and the material can be used consistently for up to 24 hours at 25°C.
3. **NOTE:** The waste of this material should not be collected into 1 pot containing a volume of >30cc as this may cause an exothermic reaction and might result even upon storage at room temperature. Waste is best disposed in the original package to avoid exothermic reactions.

Storage

Store product in the unopened container in a dry location. Storage information may be indicated on the product container labeling.

Optimal Storage: -25 to -18°C. Storage below -25°C or greater than -18°C can adversely affect product properties.

Material removed from containers may be contaminated during use. Do not return product to the original container. Henkel Corporation cannot assume responsibility for product which has been contaminated or stored under conditions other than those previously indicated. If additional information is required, please contact your local Technical Service Center or Customer Service Representative.

Conversions

(°C x 1.8) + 32 = °F

kV/mm x 25.4 = V/mil

mm / 25.4 = inches

N x 0.225 = lb

N/mm x 5.71 = lb/in

N/mm² x 145 = psi

MPa x 145 = psi

N·m x 8.851 = lb·in

N·m x 0.738 = lb·ft

N·mm x 0.142 = oz·in

mPa·s = cP

Note

The data contained herein are furnished for information only and are believed to be reliable. We cannot assume



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Reference 0.1